



DDR4 DIMM

TE Internal #: 2309408-1

Small Outline (SO), 4 mm [.157 in] Stack Height, Right Angle
 Module Orientation, 260 Position, .5 mm [.02 in] Centerline, DDR4
 DIMM, SO DIMM Sockets

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: **Small Outline (SO)**
 Stack Height: **4 mm [.157 in]**
 Module Orientation: **Right Angle**
 Number of Positions: **260**
 Centerline (Pitch): **.5 mm [.02 in]**

[All DDR4 SO DIMM Sockets \(39\)](#)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Cable-to-Board
DRAM Type	Small Outline (SO)

Configuration Features

Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	260

Electrical Characteristics

DRAM Voltage	1.2 V
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Signal Characteristics

SGRAM Voltage	1.2 V
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Body Features

Retention Post Location	Both Ends
Latch Material	High Temperature Thermoplastic



Ejector Type	Locking
Ejector Location	Both Ends
Connector Profile	Low

Contact Features

Contact Current Rating (Max)	.5 A
Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Gold Flash
Contact Mating Area Plating Material	Gold Flash

Termination Features

Insertion Style	Cam-In
Termination Method to PCB	Surface Mount

Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention Type	Solder Peg
Mating Alignment Type	Reverse Keying
PCB Mount Retention	With

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.5 mm [.02 in]

Dimensions

Stack Height	4 mm [.157 in]
Row-to-Row Spacing	8.2 mm [.322 in]

Usage Conditions

Operating Temperature Range	-55 – 85 °C [-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

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Packaging Quantity	900
Packaging Method	Tape & Reel

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Out of Scope
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | [DDR4 DIMM](#)



DIMM Sockets(13)

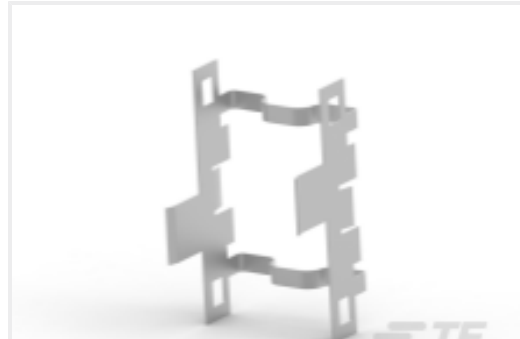


SO DIMM Sockets(39)

Customers Also Bought



TE Part #CAT-C73765-M1H
M12 Panel Mount PCB



TE Part #1367646-4
Heatsink clip Stamped and Form



TE Part #2007198-2
SFP+ 1x1 Cage Assembly, Press-Fit



TE Part #2007562-5
SFP+assy 2x6 Spring Fingers 4 LP Sn



TE Part #2170773-4
CAGE ASSY, QSFP28 1X1, QUAD, LP



TE Part #2170790-3
CAGE ASSY, 1X4, QSFP28, SPRING, HS, LP



TE Part #2198231-2
SFP+ Enhanced 1x2, SAN Heatsink, LP



TE Part #2227302-1
CAGE ASSY, PRESS FIT, SFP



TE Part #5406203-3
MJ ASSY,4P,8POS,SH,CAT5,NS P/O

Documents

Product Drawings

[DDR4 SODIMM 260P 4.0H RVS](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2309408-1_1.2d_dxf.zip](#)



English

Customer View Model

[ENG_CVM_CVM_2309408-1_1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309408-1_1.3d_stp.zip](#)

English

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Product Specifications

[Application Specification](#)

English